

台積電2025年產學合作計畫 題目

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| 3 Advancing In-Memory P-bits with SOT/STT Magnetic Tunnel Junction Technology | 10 Through controlling phase shift and inverse design to achieve mode-controllable miniaturized mode division multiplexing devices | 17 Evaluation of Neural-Network-Based and Equation-Based Approaches for Predictive IV/CV Models of 2-D Devices |
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| 6 Conductive PO basefilm formulation and film property verification | 13 Dirac source MOSFET with steep subthreshold slope | 20 To simulate small trench and nano-sheet, WET chemical clean and lateral etch behavior (MG loop, H2O2/NH4OH, TIN ALO) |
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